IN THE SPECIFICATION:

Kindly replace the first full paragraph on page 3 with the following:

As shown in FIG. 2, according to a chip of film (COF) process, a flexible printed circuit board 20 is fabricated by using an anisotropic conductive film (ACF) 21, which is electrically connected to the flexible printed circuit board 20. A circuit pattern formed with a bonding pad and a ball pad is fixedly pre-bonded to an upper surface of the flexible printed circuit board 20 by means of the anisotropic conductive film 21. An image sensor [[23]] 22 is provided above the flexible printed circuit board 20 through a flip chip bonding process. The image sensor [[23]] 22 has conductivity by means of anisotropic conductive film balls. A lens holder 24 having an infrared ray filter 23 therein is bonded to an upper portion of the flexible printed circuit board 20 through an epoxy bonding process. A lens assembly 25 is bonded to an upper portion of the lens holder 24.

Kindly replace the first full paragraph on page 7 with the following:

As shown in FIGS. 4 and 5, an image sensor module of a camera apparatus according to one embodiment of the present invention includes a circuit board 200 having transparent section [[200]] 202, an image sensor chip 500, a lens holder 600 and a lens assembly 700. A bonding section 201 is coated on an upper surface of the printed circuit board 200. A circuit pattern 300 and an infrared ray filter 400 are simultaneously bonded to an upper surface of the bonding section 201. The image sensor chip 500 is bonded to a lower portion of the printed circuit board 200 through a flip chip bonding technique. The lens holder 600 is bonded to the upper surface of the circuit board section 200 through an epoxy bonding process in such a manner that the lens assembly 700 is accommodated in the lens holder 600. The lens assembly 700 has a camera lens and is bonded to the lens

holder 600 through the epoxy bonding process. The bonding section 201 formed on the printed circuit board 200 for bonding the circuit pattern 300 and the infrared ray filter 400 is made of transparent material. Transparent material includes CU PET or CU PI. In addition, the circuit board section 200 includes a printed circuit board or a flexible printed circuit board.